SF305C 无卤阻燃型聚酰亚胺薄膜覆盖膜

SF305C Halogen-free flame-resistant type polyimide film based Coverlay

特点

- 不含卤素，阻燃性达到UL94 V-0级。
- 粘结强度高，尺寸稳定性、耐热性好。
- 溢胶量低，加工性好，适于快速压合和传统压合。
- 满足RoHS指令要求，不含铅、汞、镉、六价铬、多溴联苯、多溴联苯醚等。

应用领域

挠性印制电路板用覆盖膜。

FEATURES

- Halogen free, flammability UL94 V-0.
- High bonding strength, good dimensional stability and thermal resistance.
- Low adhesive flowing, good processability, suitable for both fast and traditional lamination style.
- Compatible with EU RoHS directive, free of Pb, Hg, Cd, Cr^{6+},PBB,PBDE, etc..

APPLICATIONS

Coverlay for FPC.

性能表 GENERAL PROPERTIES

性能项目 Test Item		试验处理条件 Treatment Condition	单位 Unit	性能数据 Property Data		
				IPC 标准值 Standard	典型值 Typical Value	
					SF305C 0515	SF305C 1025
溢胶量 Resin Flow		-	mm	-	<0.15	<0.15
剥离强度[1] Peel Strength (90°)[1]		A	N/mm	≥0.7	0.9	1.1
		288℃,5s		≥0.5	0.9	1.0
热应力[1] Thermal Stress [1]		288℃,20s	-	288℃,10s No delamination	无分层、无起泡 No delamination	无分层、无起泡 No delamination
尺寸稳定性 Dimensional Stability	MD	E-0.5/150	%	±0.2	±0.1	±0.1
	TD				±0.1	±0.1
耐化学性（剥离强度保持率） Chemical Resistance		暴露化学品后 After Chemical Exposure	%	≥80	>90	>90
体积电阻率（湿热） Volume Resistivity		C-96/35/90	MΩ • cm	$\geq 10^6$	$5.5x10^7$	$6.0x10^7$
表面电阻（湿热） Surface Resistance		C-96/35/90	MΩ	$\geq 10^4$	$3.0x10^6$	$3.5x10^6$

注释 Explanations: C = 湿热处理条件 Humidity conditioning;
E = 恒温处理条件 Temperature conditioning.

1. 与铜箔光面压合再固化后测试。Testing after laminating with shining side of copper foil in suitable condition.